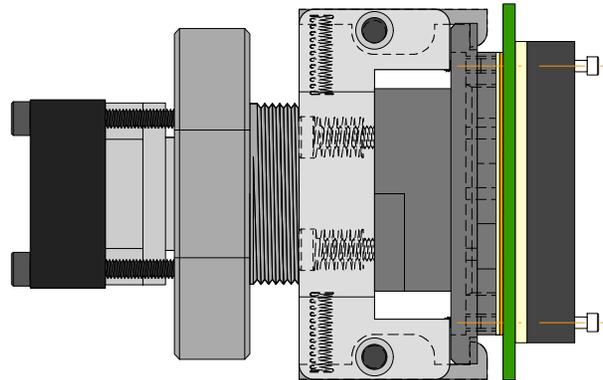
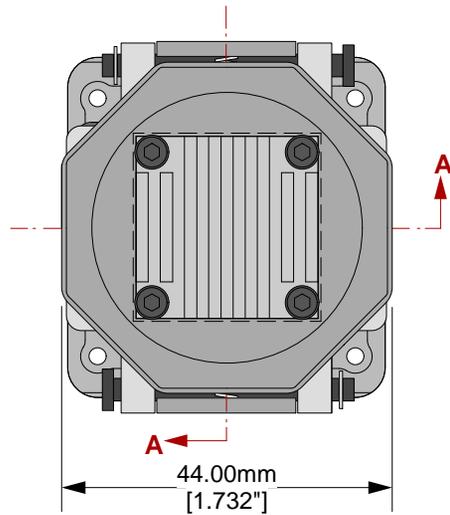
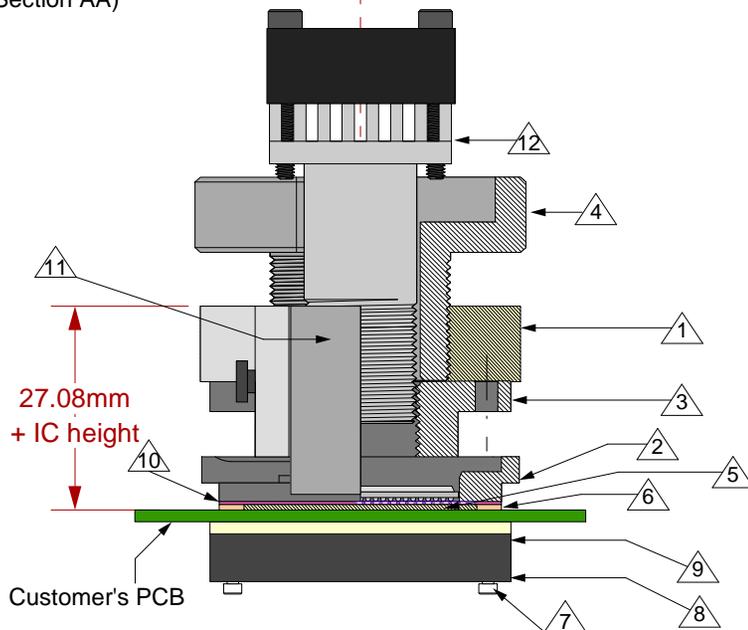


Top View



Side View
(Section AA)



Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes evenly
- Clamshell lid

Materials:

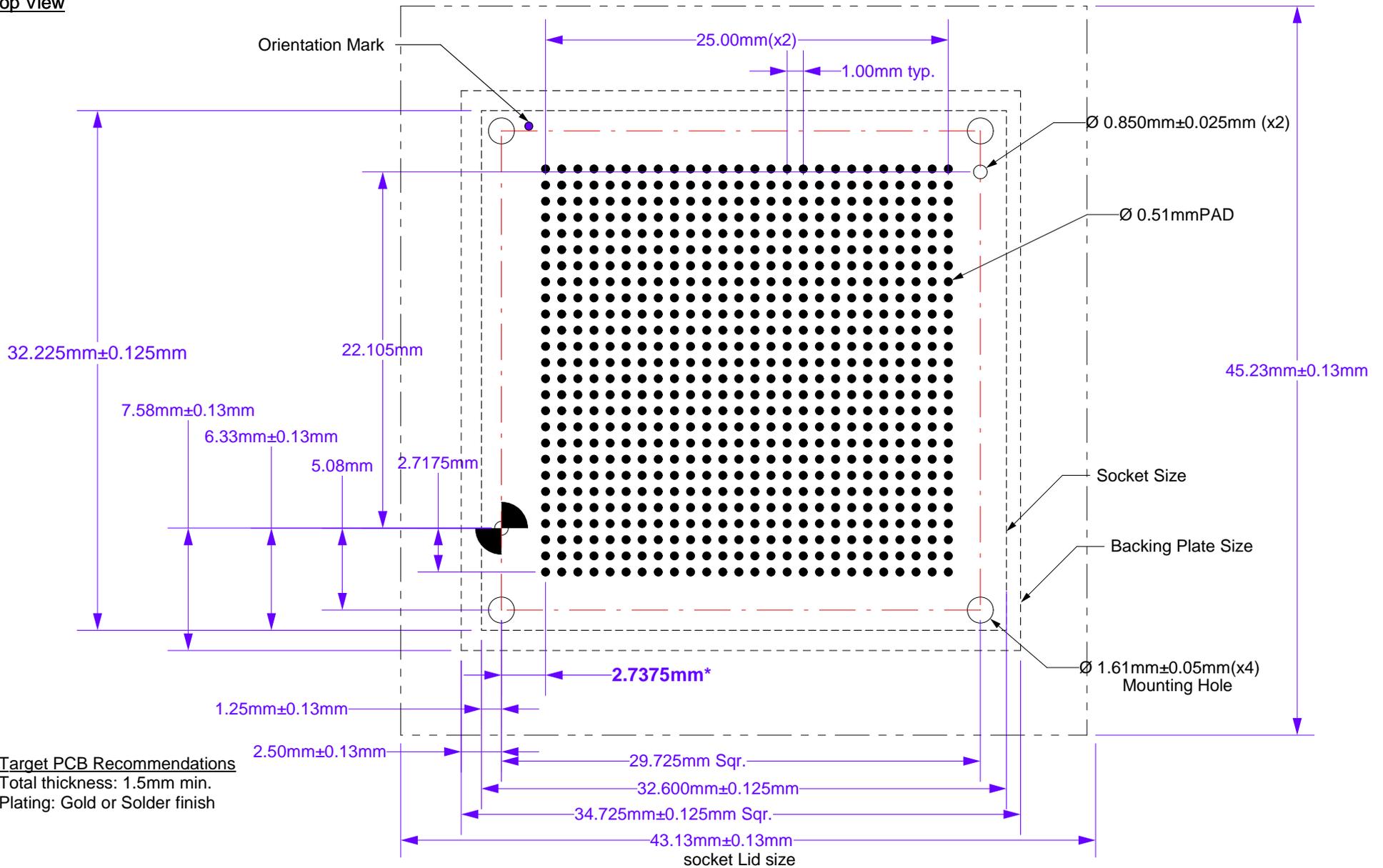
- 1 Clam Shell Lid: Black anodized Aluminum. Height = 20 mm.
- 2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 12 mm.
- 4 Compression Screw: Clear anodized Aluminum. Height = 27 mm.
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Ultem 1000. Thickness : 0.725mm
- 7 Socket Base Screw: Socket Head Cap Screw, 18-8 SS, 0-80 Thread, 1/2" long.
- 8 Backing Plate: Black anodized Aluminum
- 9 Insulation Plate: FR4/G10
- 10 Ball Guide: Kapton.
- 11 Latch: Black anodized Aluminum.
- 12 Heatsink: Aluminum

All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

 <p>CG-BGA-4004 Drawing © 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	Status: Released	Scale: 1.25:1	Rev: A
	Drawing: Vinayak R	Date: 2/17/10	
	File: CG-BGA-4004 Dwg.mcd	Modified:	

Recommended PCB Layout
Top View

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**

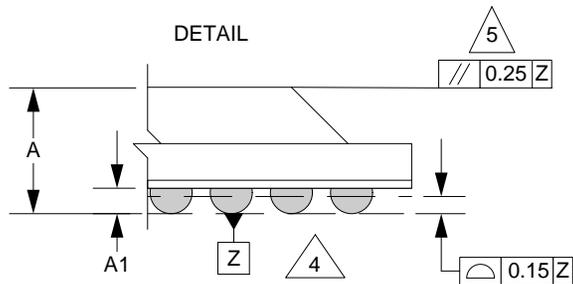
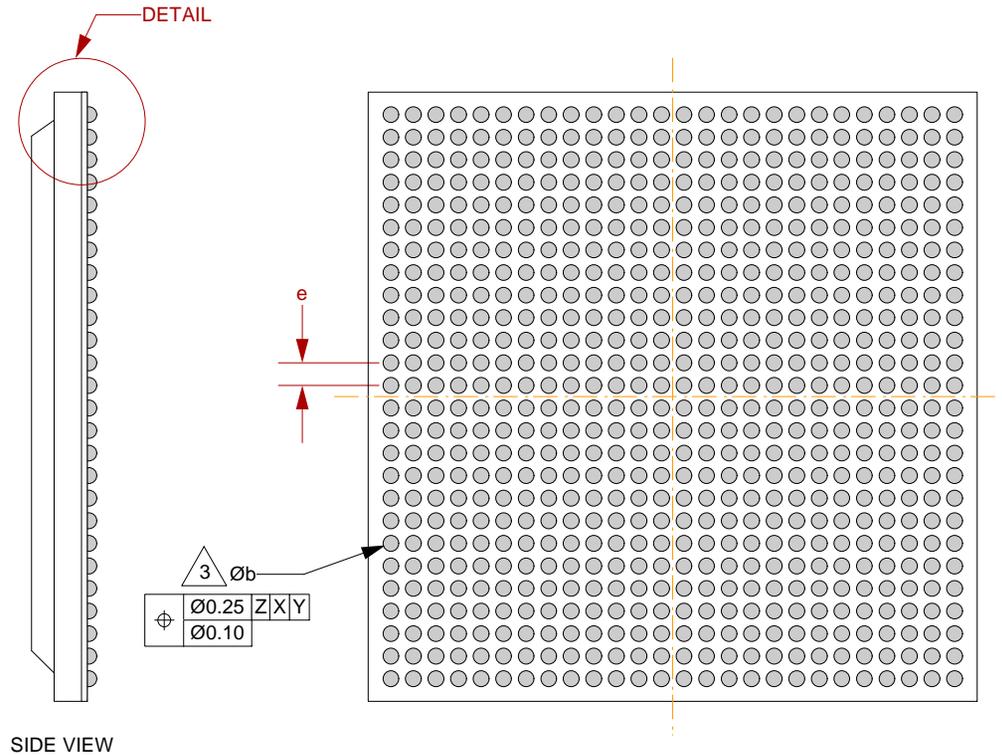
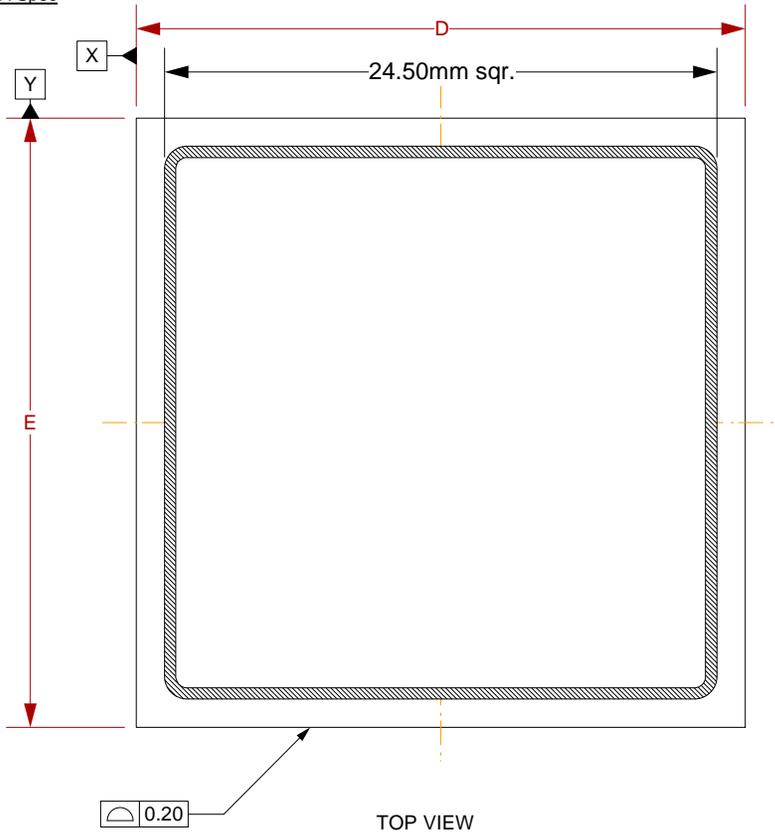


Target PCB Recommendations
Total thickness: 1.5mm min.
Plating: Gold or Solder finish

DXF DATA WILL BE PROVIDED

Recommended PCB Layout Tolerances:
±0.025mm [±0.001"] unless stated otherwise.

	CG-BGA-4004 Drawing	Status: Released	Scale: 3:1	Rev: A
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Vinayak R		Date: 2/17/10
		File: CG-BGA-4004 Dwg.mcd	Modified:	



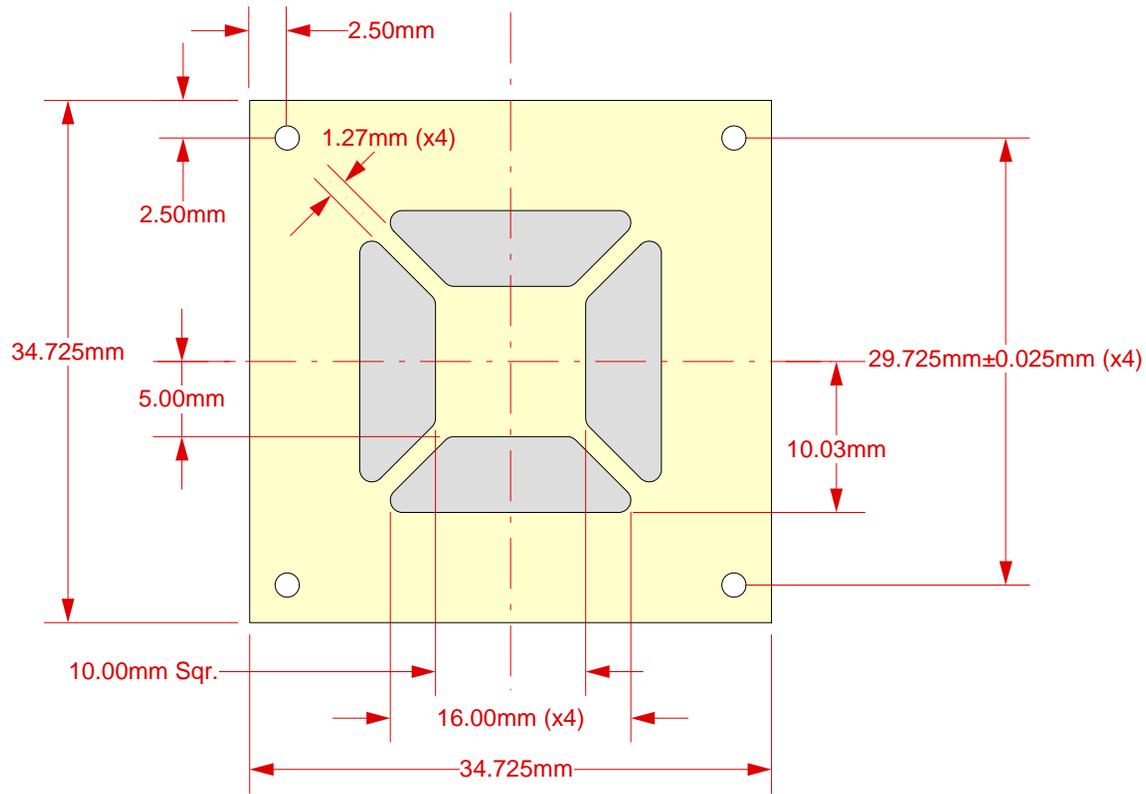
1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- $\triangle 3$ Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - $\triangle 4$ Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - $\triangle 5$ Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		4.00
A1	0.4	0.6
b	0.5	0.70
D	27.00 BSC	
E	27.00 BSC	
e	1.0 BSC	

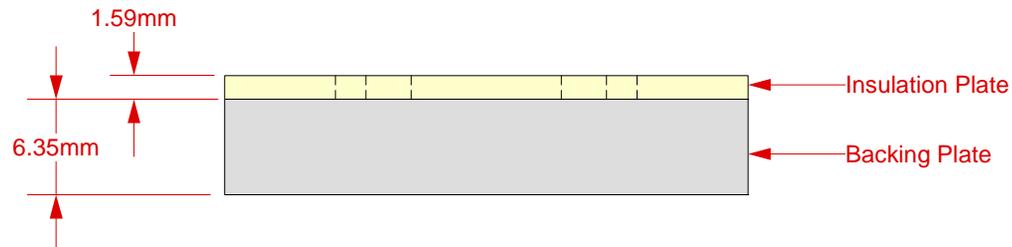
26x26 Array

 <p>© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	CG-BGA-4004 Drawing	Status: Released	Scale:	Rev: A
	Drawing: Vinayak R	Date: 2/17/10		
	File: CG-BGA-4004 Dwg.mcd	Modified:		

Top View



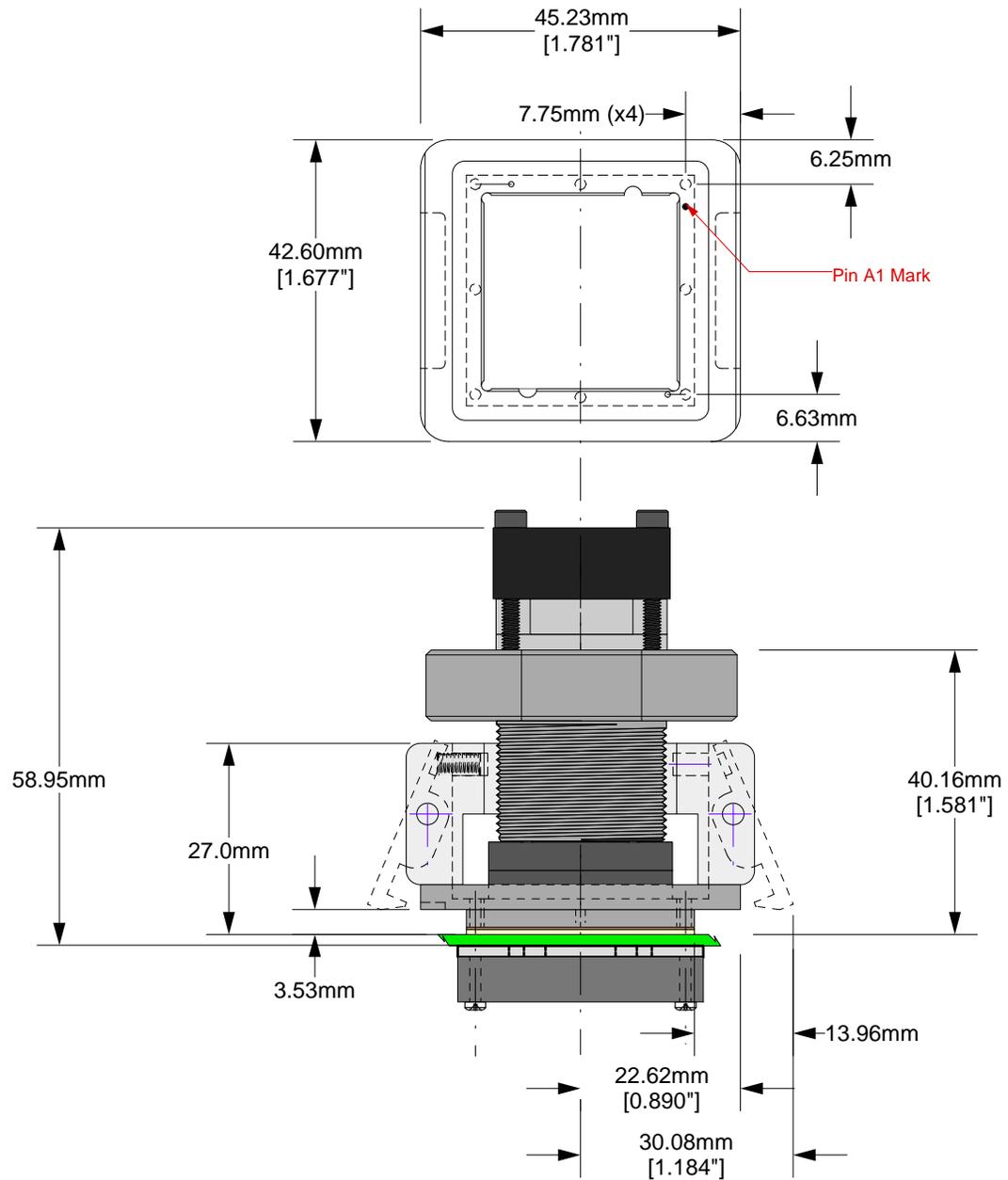
Side View



Description: Backing Plate with Insulation Plate

	CG-BGA-4004 Drawing	Status: Released	Scale:	Rev: A
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Vinayak R		Date: 2/17/10
		File: CG-BGA-4004 Dwg.mcd	Modified:	

All dimensions are in mm.
All tolerances are +/- 0.125mm.
(Unless stated otherwise)



	CG-BGA-4004 Drawing	Status: Released	Scale:	Rev: A
	© 2010 IRONWOOD ELECTRONICS, INC. Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Vinayak R		Date: 2/17/10
		File: CG-BGA-4004 Dwg.mcd	Modified:	